

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPC100N04S5-2R8	**Issued**	9. January 2019
MA#	MA001727528		
Package	PG-TDSON-8-33	**Weight***	111.64 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.614	0.55	0.55	5496	5496
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142	
	non noble metal	iron	7439-89-6	0.053	0.05		474	
	non noble metal	copper	7440-50-8	52.842	47.33	47.39	473316	473932
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	411	411
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		685	
	plastics	epoxy resin	-	6.044	5.41		54138	
	inorganic material	silicondioxide	60676-86-0	32.133	28.78	34.26	287824	342647
leadfinish	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14097	14097
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1874	1874
solder	non noble metal	tin	7440-31-5	0.018	0.02		157	
	noble metal	silver	7440-22-4	0.022	0.02		196	
	non noble metal	lead	7439-92-1	0.836	0.75	0.79	7490	7843
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2773	2777
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.828	15.07	15.09	150727	150923
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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